

# Still tearing your hair out when simulating the cost of your MEMS devices?



**COST SIMULATION  
THAT MAKES YOU COOL**



WEBCAST

when: JUNE 4th

time: 5:00 PM CET



System Plus Consulting breaks this barrier creating **a revolutionary costing tool "MEMS Price +"**. Get rid of the extreme variability of MEMS processes! This tool gives you a cost model mixing global parameter and Technologies. To know more about this tool, **join our webcast** and discover in live the power of the MEMS Price + costing tool.

System Plus Consulting has published more than 100 devices reverse costing reports on MEMS, and has used its expertise to propose an efficient and easy-to-use cost simulation tool able to simulate most of the MEMS technologies from the main players. MEMS Price+ allows anyone from purchasing & marketing departments, but also costing & R&D departments, to calculate the production cost and selling price of a wafer, die, packaged MEMS or System-in-Package including an unlimited number of dies. A fine knowledge of the MEMS or IC processes is no more necessary to get an accurate cost. The tool also offers the possibilities for forecast and for simulating MEMS processes on wafer size up to 12-inch.

**During this live session, we will demonstrate how to take advantage of MEMS Price+ to evaluate the cost of MEMS devices. The presentation will be based on a live demo with an actual MEMS example analyzed by System Plus Consulting.**

Speaker:



Romain Fraux is Project Manager for Reverse Costing analyses at System Plus Consulting. Since 2006, Romain is in charge of costing analyses of MEMS devices, Integrated Circuit and Advanced Packaging. He has significant

experience in the modeling of the manufacturing costs of electronics components and has published more than 50 Reverse Costing reports on various MEMS devices including Inertial, Pressure, Microphones or RF Sensors.

Romain has a BEng from Heriot-Watt University of Edinburgh, Scotland and a master's degree in Microelectronics from the University of Nantes, France.

Moderator:



Steven LaFerriere serves as Director of North America Business Development at Yole Développement. Steven has more than 20 years of experience as a sales executive in the electronics marketplace, with an outstanding track record of customer problem solving. Prior to joining Yole Développement in January 2015, he was a Senior Account Manager at IHS Corporation. His career also includes marketing positions and technical sales support at Avnet Electronics. Steven is a graduate of California State University Long Beach in Southern California.



# Still tearing your hair out when simulating the cost of your MEMS devices?



**COST SIMULATION THAT MAKES YOU COOL**

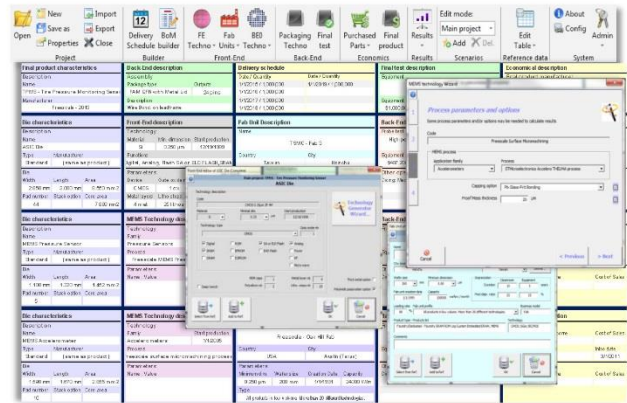


## MEMS PRICE+: INPUTS/OUTPUTS

(Source: MEMS Price+, System Plus Consulting, 2015)

### INPUTS

- **Parts description** IC or MEMS, die dimensions
- **Fab Unit description** profile, wafer size, minimum technology size, clean room & equipment parameters
- **Technology description**, substrate, process parameters OR device type, transistor size, functions, building processes details
- **Wafer backend details**, temperature range & test flow, back grinding, bumping and dicing, technologies, and parameters, probe test equipment
- **Assembly options**, Package characteristics, panelization parameters, PCB description, wire bonding parameters and other options
- **Final test details**
- **Manufacturer & foundry financial statements**
- **Commercial data** delivery schedule, market position of the component, life cycle details, quantity / price data



### OUTPUTS

- **Wafer cost breakdown** manufacturing cost, raw wafer cost, labor cost, yield losses...
  - **Die cost breakdown**
  - **Assembly cost breakdown**
  - **Component cost breakdown**
  - **Yields versus time**
  - **Manufacturing cost versus time**
  - **Selling prices versus time**
- Up to 5 scenarios



**MEMS Price+**

Powered by:



Hosted by:

**i-Micronews**